FOR IMMEDIATE RELEASE

HDP User Group Announces "The Latest Findings on Tin Whiskers in Electronics"

Thursday, October 29 at 10AM US Central Time (Webex)

Cave Creek, Arizona September 21, 2015. The High Density Packaging (HDP) User Group headquartered in the United States is pleased to announce its sponsorship of a free Webinar that will provide the latest findings on Tin Whiskers in Electronics.

The NASA tin (Sn) whisker web site describes Sn whiskers as electrically conductive, crystalline structures of tin that sometimes grow from surfaces where tin (especially electroplated tin) is used as a final finish. Numerous electronic system failures have been attributed to short circuits caused by tin whiskers that bridge closely-spaced circuit elements maintained at different electrical potentials.

Dave Love, Project Facilitator for HDP User Group states "The purpose of this Webinar is to share recent developments regarding tin whiskers, particularly with respect to the use of SAC solders. Topics to be covered include whisker growth mechanisms, real life failure histories, and whisker mitigation strategies."

Top people in the field will give presentations and participate in a short Q&A session at the end of the webinar. The Q&A session will use questions submitted by email. Only the panel will be unmuted.

Planned Agenda:

- Brief introduction and welcome - D. Love (HDP User Group)
- Mechanisms for Nucleation and Growth of Tin Whiskers: Implications for Finding Practical Solutions; Carol Handwerker (Purdue University), Eric Chason (Brown University)
- Issues and Corrective actions for those using SAC solder and tin surface finishes; Polina Snugovsky (Celestica)
- Real-life examples and mitigations, Mil-Aero perspective: Michael Osterman (CALCE)
- Wrap-up: Carol Handwerker
- Q&A Session moderated by Dave Love

If you miss the webinar, don't worry! A recording will be made available.
Thanks to the following co-sponsors for their support: SMTA, IPC, EIPC, SEMI, CALCE, and MEPTEC.

To register for the Webinar, the Direct link for registration is:
http://www.smta.org/education/registration/event_registration.cfm?event_id=1208
or contact David Love at dave49@hdpug.org

Send questions before the meeting to dave49@hdpug.org for the Q&A session.

About HDP User Group

HDP User Group (www.hdpug.org) is a global research and development organization based in Cave Creek Arizona, is dedicated to "reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly". This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas; and Stockholm, Sweden.

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963.